Denso Lexus GS250 TCU Teardown

FEATURES:

- Telematics Control Unit
- CDMA
- Cypress MB91F577BH, 32-bit, 80MHz



Click here for detailed data from Fomalhaut's teardown analysis.



Denso
86741-53045
-
unknown
Unknown
2015.??.??
1113 - Tachiyomi

SPECIFICATIONS



manufactured by Denso for Lexus U.S. model. Functions; Emergency connection to Police and Emergency Units, with a button. Format; CDMA Supporting 800MHz (high diffraction) and 1900MHz (high straight-stability).

BASIC	Product Name Lexus GS250 TCU, 86741-53045							
	Manufacturer	Denso Corporation 139.9 x 118.9 x 28.8 417						
	Minimum Size (mm)							
	Weight (g)							
BATTERY TIME	Standby (hours)	3.9G: FDD-LTE: -	3.9G: TD-LTE: -	3G: WCDMA: -	3G: CDMA: ?	3G: TD-SCDMA: -	2G: GSM:	
	Voice Call (minutes)	3.9G: FDD-LTE: -	3.9G: TD-LTE: -	3G: WCDMA: -	3G: CDMA: -	3G: TD-SCDMA: -	2G: GSM: -	
	Video Call (minutes)	-						
	Digital TV (minutes)	-						
	Other	-						
	Battery (size in mm)	-						
SYSTEM	os	unknown						
	CPU / ROM / RAM	CPU: Cypress (Fujitsu	ı) MB91F577BH, 32-bi	t, 80MHz				
		ROM: 256MByte + 25	6MByte					
		RAM: 128MByte	·					
DISPLAY								
	Sub Display	-						
COMMUNICATION	Protocol (MHz)	3.9G: FDD-LTE: -						
	, ,	3.9G: TD-LTE: -						
		3G: WCDMA: -						
		3G: CDMA: 800, 1900 3G: TD-SCDMA: -						
		2G: GSM: -						
	HSDPA/HSUPA (Mbps)	os) 3G: unknown LTE: -						
	Wireless LAN	-			•			
	Bluetooth							
	GPS	Yes						
	Infrared	-						
	RFID/NFC							
CAMERA	Main Camera							
	Sub Camera	-						
SENSOR	Motion	Accelerometer: -	Digital Com	npass: -	Gyroscope: -	Barometer	-	
		Gesture Recognition:			-	-		
	Ambient	Light Sensor: -	Proximity S	ensor: -	Temperature Senso	r: - Humidity S	ensor: -	
	Security	Fingerprint Sensor: -	-		-	-		
	Healthcare	Heart Rate Monitor: -						
	Touch Panel	-						
OTHER	HDMI	-						
	MicroSD (max capacity)	-						
	Waterproof/Anti-shock	-						

OUTLOOK / PRODUCT INFORMATION



The inscription shows name of supplier; Denso.

Production country; unknown.

Installed under the driver or front passenger seat

(estimation)

Housing; Aluminum alloy











TEARDOWN



Housing; Aluminum, implementing a circuit board inside.

Reason to use the metal housing; shielding of noise not to disturb transmission of electric wave.

The circuit board consists of a big main one plus island-like sub boards on the main one,

The island-like boards associated with telecommunication.

Top Cover PCB#1







Bottom Cover

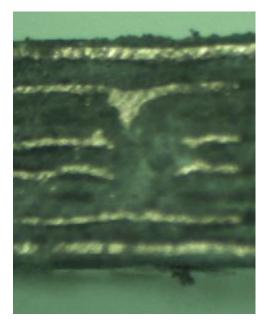


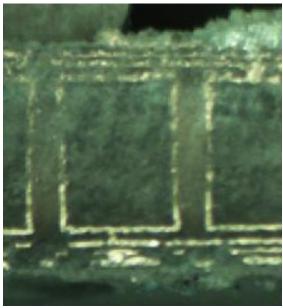
The boards associated with telecommunication have inscription "Sierra Wireless" (a communication module supplier in Canada) Many on-board TCU adopt the supplier.

	PCB #1	PCB #2	-	-	-	-
Manufacturer	unknown	unknown	-	-	-	-
Dimension	130.55 x 95.89 x 1.56	40.21 x 40.26 x 1.51	-	-	-	-
Layer	6	8	-	-	-	-
Connector (pin)	0	0	-	-	-	-
Connector (socket)	4	0	-	-	-	-
Connector (ACF)	0	0	-	-	-	-



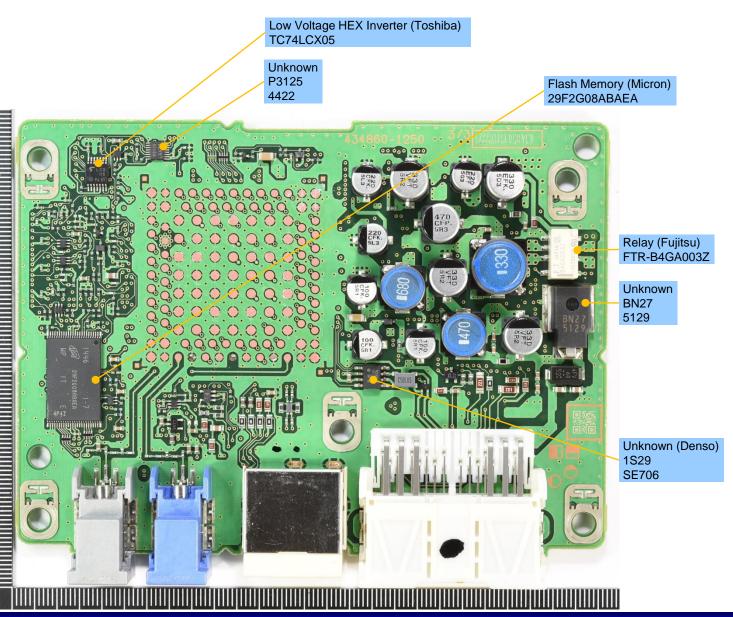








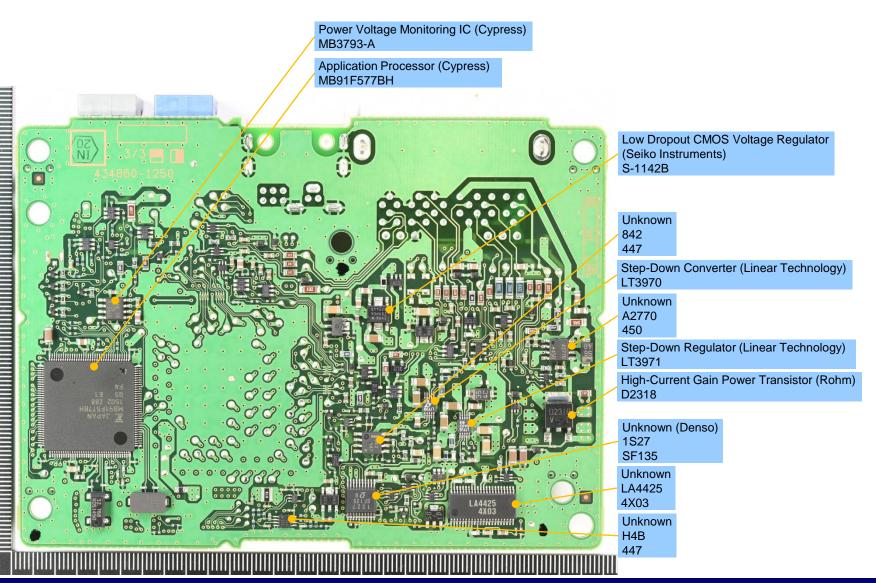
The big main board is mounted components associated with interface (between vehicle system and TCU), antenna socket and system power supply.





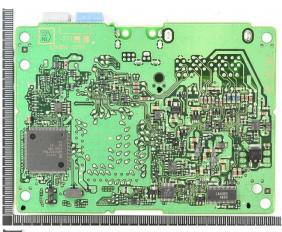
The big chip on the bottom left in the photo is a micro-computer, 32-bits which is associated with communication to other vehicle components on the vehicle.

Price circa \$ 4. Many chips on the right side of the board are functioning as system power supply.



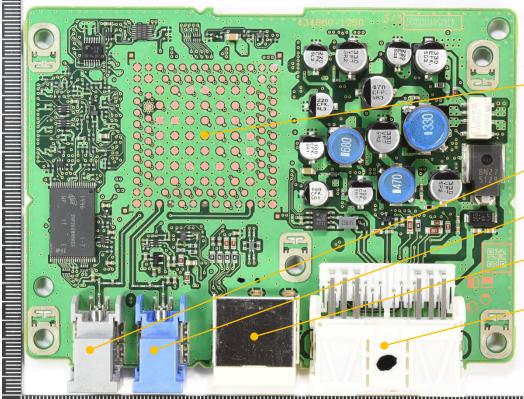
PCB#1: CONNECTORS





Central portion of the board has many soldering points which are planned to mount small boards. (refer to fornt & back side photos on the left below)

Also some points are for testing of the small board, for probe-touching for diagnosis.



	Connecting to	PCB#2				
	Mnf.	-	L (mm)	-		
	Pin Pitch (mm)	-	W (mm)	-		
	Pin #	133	(H) (mm)	-		
	Connecting to	Antenna Port (CDMA)				
	Mnf.	Sumitomo	L (mm)	24.56		
	Pin Pitch (mm)	-	W (mm)	13.08		
	Pin #	1	(H) (mm)	12.80		
	Connecting to	Antenna Port	(CDMA)			
	Mnf.	Sumitomo	L (mm)	25.64		
	Pin Pitch (mm)	-	W (mm)	13.04		
	Pin #	1	(H) (mm)	12.75		
	Connecting to	Input / Output				
	Mnf.	JAE	L (mm)	23.50		
	Pin Pitch (mm)	-	W (mm)	21.21		
	Pin #	8	(H) (mm)	11.96		
	Connecting to	Input / Output				
	Mnf.	unknown	L (mm)	32.41		
	Pin Pitch (mm)	-	W (mm)	40.23		
	Pin #	38	(H) (mm)	11.28		

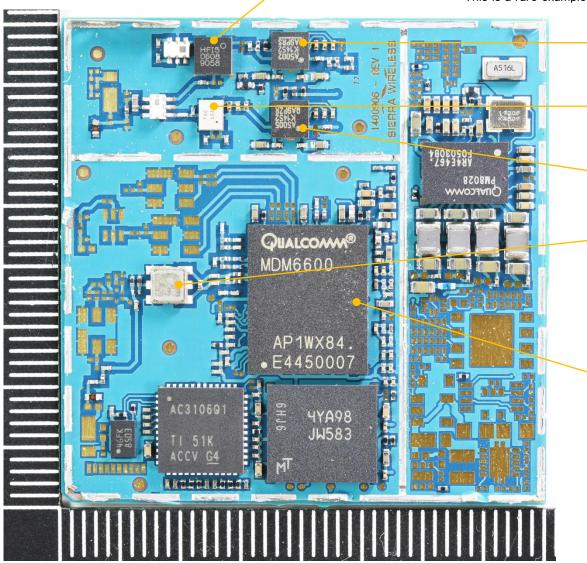


3G Module GTM-3 (Sierra Wireless) Filter (mnf. unknown) HFI5 0608 9058 Communication components are intensively mounted on a small board on the main board.約。

Qualcomm chip set is adopted.

Qualcomm MDM6600 is a processor for telecommunication, which also function as telematics IC and GPS, like Phone 4S.

This is a rare example of BGA mounting for an on-vehicle with many QFPs.



CDMA Power Amplifier (Avago) ACPM-5002

Filter (mnf. unknown)
PA6
b04

CDMA Power Amplifier (Avago) ACPM-5005

SAW Filter (TDK) B3517

Baseband Processor + CDMA Transceiver + GPS (Qualcomm) MDM6600

PCB#2 SIDE A: KEY COMPONENTS

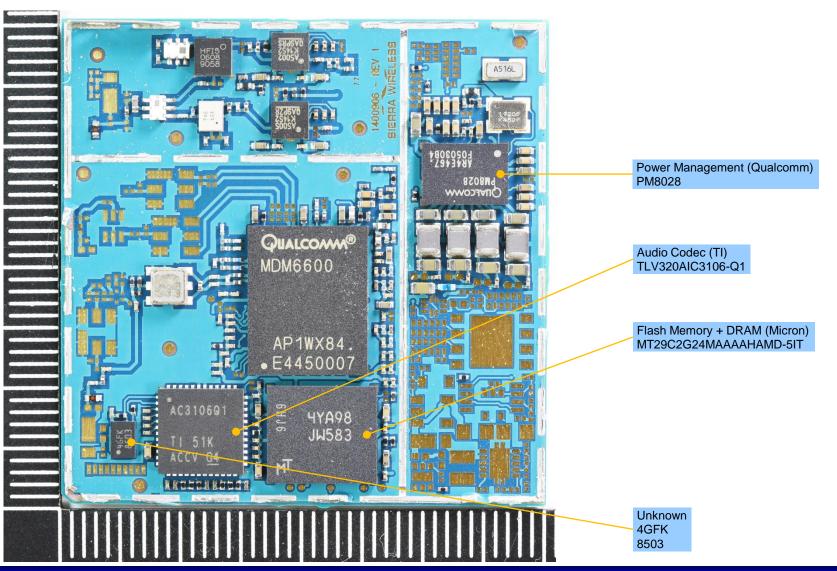




Power supply IC for telecommunication is Qualcomm PM8028.

Implementing audio- for controlling of voice signal. Though the TCU body does not have a mike, is connected to mikes implemented on other part of vehicle, which is potentially expected to realize voice communication as well as emergency signal.

In that case, TCU is able to be utilized as a concierge and be asked search of a restaurant in the vicinity ...,etc.



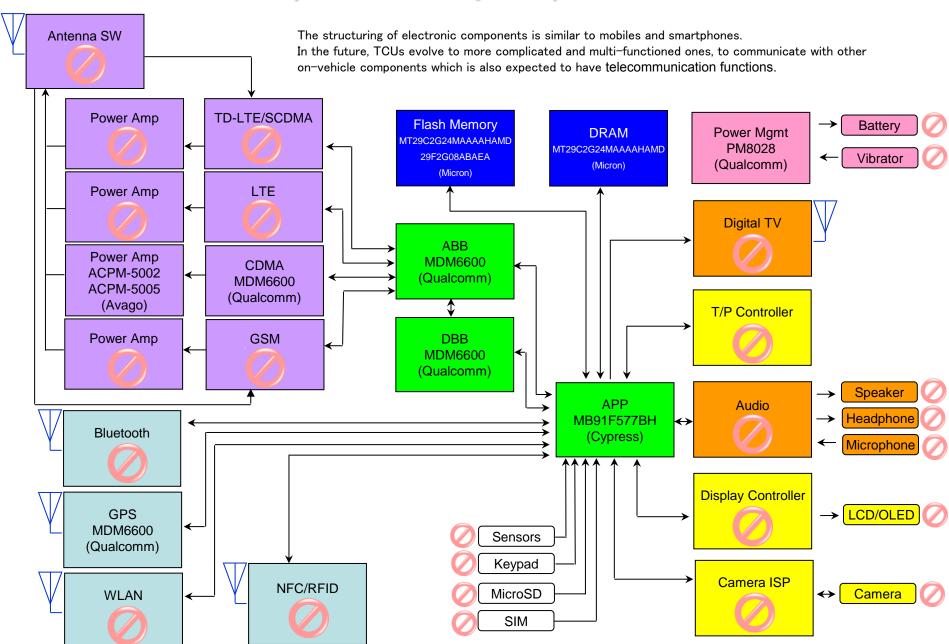


The telecommunication board has sigle-sided mounting. The reverse side is utilized for connection to the mating big board.



BLOCK DIAGRAM (with assumption)







SERVICES

- TEARDOWN: on cellular phone, smartphone, tablet, laptop PC, digital still camera, LCD TV, and other mobile equipments.
- BILL OF MATERIALS: all-component-cost breakdown into more than 100 categories.
- MARKET REPORT: based on requests.
- SEMINAR: based on requests. Free seminars offered to regular subscribers every quarter.
- INTELLECTUAL PROPERTY: old phones available since 1996 up to date. Most of them are functional.

DISCLAIMER

- 本レポートは、一般市場にて購入した製品を分解し、搭載されている部品の特定及び機能分析を限られた情報の中で行ったものです。フォーマルハウトは、法律の規定により免責が認められない場合を除いて、お客様が本レポートのご利用により損害(データの内容・業務の中断・営業情報の損失などによる損害や第三者からの賠償請求の可能性を含む)が生じたとしても、一切責任を負うものではありません。あらかじめご了承ください。
- This report features products purchased in the consumer market, and contains component identity and its functional information which has been prepared under limited access to the information source. Fomalhaut releases this report from any liability for possible damage (such as loss of data contents, suspension of the business, loss of information, and litigation from the third party) except being deemed legally responsible.
- 本レポートの記載内容は、主に製品が発売された当初のものです。そのため、マイナーチェンジなどの理由により、本レポートの記載内容が最新の端末の内容を反映したものではなくなる可能性があります。あらかじめご了承ください。
- The contents of this report, except specified, reflects the first-lot-product information. Minor changes may cause differentials of the report contents from the latest product.

LEGAL

- 本レポートは、日本国「輸出貿易管理令別表1及び外国為替令別表の規定に基づき貨物又は技術を定める省令」に関し、1~15項の該非判定は「対象外」です。判定事由は、「輸出貿易管理令 別表第1」の1項~15項に該当項目がないためです。
- This report, as per Japan's "Export Trade Control Ordinance" and "Foreign Exchange Order," does not apply to items 1 thru 15 for the report contents do not match any of these items on "Export Trade Control Ordinance."
- 本レポートは、「米国輸出管理規制(EAR)」に関する再輸出規制調査に関し、判定結果は「対象外」です。
- This report, as per the United States Export Administration Regulations, does not apply to re-export regulation.

発行者: フォーマルハウト・テクノ・ソリューションズ Office: 〒135-0061 東京都江東区豊洲4-10-4-1301

担当者: 柏尾 南壮 (Kashio, Minatake)

Phone: 03-6759-4289 Fax: 03-6219-4005

E-mail: minatake kashio@fomalhaut.co.jp

Published by: Fomalhaut Techno Solutions

Office: 4-10-4-1301, Toyosu, Koto-ku, Tokyo 135-0061, Japan

Contact: Minatake Kashio (Director)

Phone: +81-3-6759-4289 Fax: +81-3-6219-4005

E-mail: minatake_kashio@fomalhaut.co.jp



Website: http://www.fomalhaut.co.jp

Click here for detailed data from Fomalhaut's teardown analysis.